

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3491451

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DOO-HOON SUN	08/19/2015
YONG-SIK KIM	08/19/2015
JUNG-SUNG KIM	08/18/2015
TAE-JIN SHIN	08/18/2015
BYUNG-SOO KIM	08/18/2015
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14831159
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ATTORNEY DOCKET NUMBER:	15813.23.1
NAME OF SUBMITTER:	DANA L. TANGREN
SIGNATURE:	/dana l. tangren/
DATE SIGNED:	08/20/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	

PATENT

Total Attachments: 4

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COMBINED DECLARATION and ASSIGNMENT
(Utility, Design, National Stage of PCT)

TITLE OF INVENTION:² METHOD FOR MANUFACTURING IMPLANT HAVING
POROUS LAYER ON SURFACE THEREOF

As a below named inventor, I hereby declare that:

SPECIFICATION IDENTIFICATION

This declaration and assignment is directed to:

(complete (a), (b), or (c))³

- (a) ☒ The attached application (United States Application No. 14/831,159,
filed on August 20, 2015);
- (b) ☐ Previously filed United States Application No. _____,
filed on _____; or
- (c) ☐ PCT International Application No. _____,
filed on _____ (nationalized as United States Application No.
_____, filed on _____).

I hereby authorize the patent attorneys and/or patent agents of Workman Nydegger to insert the
above Application No(s). and filing date(s) when known.

DECLARATION AND ACKNOWLEDGEMENT

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
above-identified application.

I hereby state that I have reviewed and understand the contents of the above-identified
application, including the claim(s).

I acknowledge the duty to disclose all information which is material to patentability as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT⁴

The Assignee, CORENTEC CO., LTD, having a principal place of business at 247 Giro-ri, Ipjang-myeon, Seobuk-gu, Cheonan-si, Chungcheongnam-do, Republic of Korea 331-822, desires to secure the entire right, title and interest in the above-identified application.

In consideration of One Dollar (\$1.00) and other good and valuable consideration paid to me by the Assignee, the receipt and sufficiency of which is hereby acknowledged, I HEREBY ASSIGN TO THE ASSIGNEE:

The entire right, title and interest in the above-identified application and in all divisions, continuations and continuations-in-part of said application and in all patents issuing thereon in the United States and in all reissues or extensions of patents granted thereon.

The right to claim priority to or the benefit of any prior related United States or foreign patent applications including under all applicable treaties and conventions.

I hereby authorize and request the United States Commissioner of Patents and Trademarks, to issue any and all patents on said application to the Assignee as the owner of the entire interest, for the sole use and behoof of the said Assignee, its successors, assigns and legal representatives.

I hereby agree, without further consideration, to sign all lawful papers and to perform all other lawful acts which the Assignee may request me to make this Assignment fully effective, including, by way of example but not of limitation, the following:

Prompt execution of all original, divisional, continuation, continuation-in-part, substitute, reissue, and other United States applications and all lawful documents requested by the Assignee to further the prosecution of any of such patent applications.

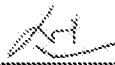
With regard to the above-identified application and applications claiming priority thereto, cooperate to the best of my ability in: (1) proceedings relating to nullification, reissue, extension, post grant, inter parties, derivation, supplemental examination, and infringement; (2) execution of all lawful documents; and (3) the production of evidence.

This assignment and agreement shall be binding upon my heirs and legal representatives.

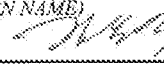
SIGNATURE(S)⁵

NOTE: Carefully indicate the family (or last) name, as it should appear on the filing receipt and all other documents.

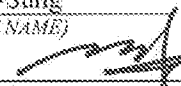
Full name of sole or first inventor

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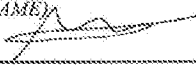
Full name of second joint inventor, if any

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
Full name of third joint inventor, if any

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Full name of fifth joint inventor, if any

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